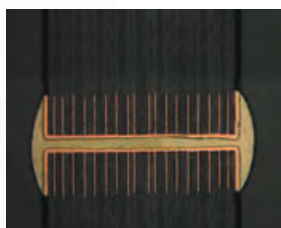
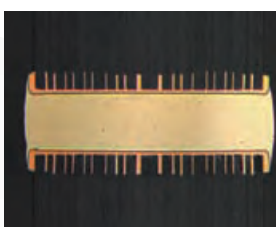
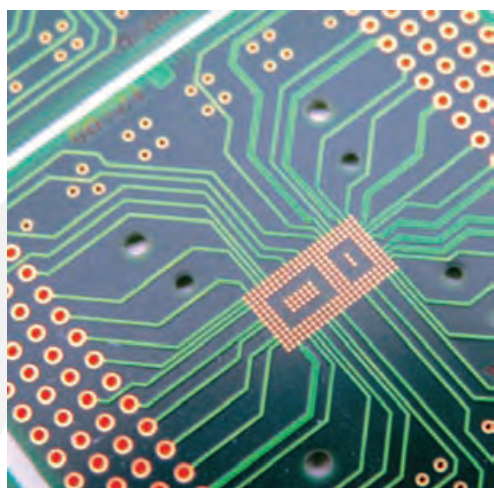


ALWAYS CLOSE TO YOUR NEEDS!



Multilayer PCBs

Production plants:

Elco Italy, Elco France,
Elco Europe (Spain), Elco China

Description:

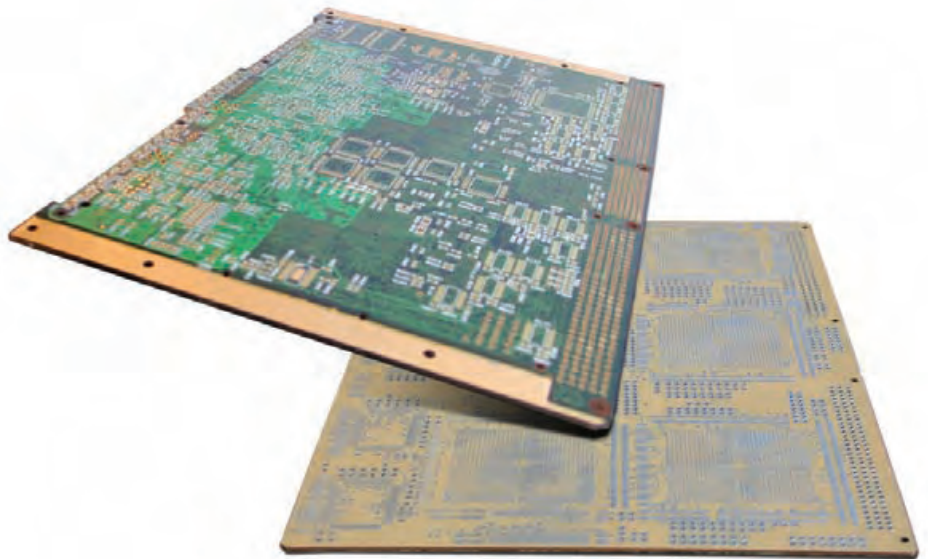
Homogeneous and
Composite Rigid Multilayer circuit boards:

(Homogeneous) :

Rigid multilayer circuit boards composed
of the same base material

(Composite) :

Rigid multilayer circuit boards composed
of different base materials



Technical Data:

Construction

Up to 38 layers (under consideration
of the maximum pcb thickness)
Standard base copper thickness:
18 μm , 35 μm , 70 μm , 105 μm

Base Material

FR4 Std Tg 135°
FR4 Medium Tg > 150°
FR4 Hi Tg > 175°
Polyimide
Teflon substrates
(Special materials on request)

Dimensions

Maximum pcb size: 640 x 570 mm

PCB Thickness

Maximum pcb thickness: 6,5 mm
Minimum pcb thickness: 0.3 mm

Surfaces Finishing

- Organic copper-passivation
 - Hot air levelling (HASL)
(depends on thickness and size)
 - Electroless nickel/gold (NiAu)
 - Electroplated nickel/gold (NiAu)
 - Tin Lead reflow
- Other surfaces on request

Solder Masks

- Screen printing of solder mask
(uv-drying)
- Peelable solder mask

Special Printings

- Carbon
- Marking print

Track Width/Space

Standard: 100 μm
High Tech: 75 μm
Next Step: 50 μm

Drill Diameter (mechanical)

Standard : 200 μm
High-Tech: 150 μm
Next step: 75 μm

Microvia Technology

(laser drilled blind via)
Standard Drill Diameter: 75 μm
Aspect ratio: ≤ 1

Contour Processing

- Milled
- Scored (contour or perforation)

Impedance Check

- On request
- Tolerance of impedance: $\pm 10\%$

Tests

- Automatic-Optical-Inspection
(depending on layout and surface)
- 100 % electrical test
- Special check on request
- Visual inspection

Quality Controls

- Guarantee of custom-designed quality
standards and production according
to international guidelines:
- Vision 2000 - CNES - AS9100B
- EN9100:2003/S1 - JISQ9100:2004
- UL Certified: 94V-0 up to 130°